

Disco DFL7360 Laser Dicing Saw (Stealth)

- Hansen cut: Yes
- Chiller unit: Yes
- UPS unit: Yes
- Wafer mapping: No
- Wafer ID read function: Yes
- FOUP Barcode read function: Yes
- Sec/Gems capable: Yes
- Air Ionizer Unit: Yes
- Wafer handling: FOUP/FOSB
- Touch Screen Display GUI interface: Yes
- Laser Specification:
 - Oscillator model: Semiconductor excitation Q-switch solid laser
 - Oscillation formation: Pulse
 - Laser wavelength: 1064nm



Micron Tool ID	Micap # 1168416	AGSS / Adelis Tool ID	RMMT20163
Manufacturer	Disco	Model	DFL7360
Serial Number	KP1027	Process	Laser Dicing (Stealth)
Vintage		Wafer Size	300mm
Current Status	De-Installed	Location	Singapore (MSB)